# **General Purpose Transistors**

## **NPN Silicon**

#### **Features**

• Pb-Free Package is Available

#### **MAXIMUM RATINGS**

| Rating                         | Symbol    | Value | Unit |
|--------------------------------|-----------|-------|------|
| Collector - Emitter Voltage    | $V_{CEO}$ | 25    | V    |
| Collector - Base Voltage       | $V_{CBO}$ | 30    | V    |
| Emitter-Base Voltage           | $V_{EBO}$ | 5.0   | V    |
| Collector Current – Continuous | Ic        | 500   | mAdc |

### THERMAL CHARACTERISTICS

| Characteristic   | Symbol                            | Max         | Unit        |
|--|-----------------------------------|-------------|-------------|
| Total Device Dissipation FR-5 Board,<br>(Note 1) T <sub>A</sub> = 25°C<br>Derate above 25°C  | P <sub>D</sub>                    | 225<br>1.8  | mW<br>mW/°C |
| Thermal Resistance,<br>Junction-to-Ambient   | $R_{\theta JA}$                   | 556         | °C/W        |
| Total Device Dissipation Alumina Substrate, (Note 2) T <sub>A</sub> = 25°C Derate above 25°C | P <sub>D</sub>                    | 300<br>2.4  | mW<br>mW/°C |
| Thermal Resistance,<br>Junction-to-Ambient   | $R_{\theta JA}$                   | 417         | °C/W        |
| Junction and Storage Temperature   | T <sub>J</sub> , T <sub>stg</sub> | -55 to +150 | °C          |

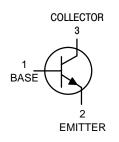
Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

- FR-5 = 1.0 x 0.75 x 0.062 in.
   Alumina = 0.4 x 0.3 x 0.024 in 99.5% alumina.



### ON Semiconductor®

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SOT-23 **CASE 318** STYLE 6

#### MARKING DIAGRAMS



6G = Specific Device Code

M = Date Code\*

= Pb-Free Package

(Note: Microdot may be in either location)

\*Date Code orientation and/or overbar may vary depending upon manufacturing location.

### ORDERING INFORMATION

| Device       | Package             | Shipping <sup>†</sup> |
|--------------|---------------------|-----------------------|
| BC818-40LT1  | SOT-23              | 3000 / Tape & Reel    |
| BC818-40LT1G | SOT-23<br>(Pb-Free) | 3000 / Tape & Reel    |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# **ELECTRICAL CHARACTERISTICS** ( $T_A = 25^{\circ}C$ unless otherwise noted)

|   |                      |           |        | T          | T        |
|---|----------------------|-----------|--------|------------|----------|
| Characteristic  | Symbol               | Min       | Тур    | Max        | Unit     |
| OFF CHARACTERISTICS   |                      |           |        |            |          |
| Collector – Emitter Breakdown Voltage (I <sub>C</sub> = –10 mA)   | V <sub>(BR)CEO</sub> | 25        | _      | _          | V        |
| Collector – Emitter Breakdown Voltage (V <sub>EB</sub> = 0, I <sub>C</sub> = –10 μA)  | V <sub>(BR)CES</sub> | 30        | _      | -          | V        |
| Emitter – Base Breakdown Voltage (I <sub>E</sub> = –1.0 μA)   | V <sub>(BR)EBO</sub> | 5.0       | -      | -          | V        |
| Collector Cutoff Current $(V_{CB} = 20 \text{ V})$ $(V_{CB} = 20 \text{ V}, T_A = 150^{\circ}\text{C})$                     | I <sub>CBO</sub>     | -<br>-    | -<br>- | 100<br>5.0 | nA<br>μA |
| ON CHARACTERISTICS  |                      |           |        |            |          |
| DC Current Gain<br>( $I_C = 100 \text{ mA}, V_{CE} = 1.0 \text{ V}$ )<br>( $I_C = 500 \text{ mA}, V_{CE} = 1.0 \text{ V}$ ) | h <sub>FE</sub>      | 250<br>40 | _<br>_ | 600<br>-   | -        |
| Collector – Emitter Saturation Voltage<br>(I <sub>C</sub> = 500 mA, I <sub>B</sub> = 50 mA)                                 | V <sub>CE(sat)</sub> | -         | _      | 0.7        | V        |
| Base – Emitter On Voltage<br>(I <sub>C</sub> = 500 mA, V <sub>CE</sub> = 1.0 V)   | V <sub>BE(on)</sub>  | -         | -      | 1.2        | V        |
| SMALL-SIGNAL CHARACTERISTICS  |                      |           |        |            |          |
| Current-Gain - Bandwidth Product<br>(I <sub>C</sub> = 10 mA, V <sub>CE</sub> = 5.0 Vdc, f = 100 MHz)                        | f <sub>⊤</sub>       | 100       | _      | _          | MHz      |
| Output Capacitance $(V_{CB} = 10 \text{ V}, f = 1.0 \text{ MHz})$   | C <sub>obo</sub>     | -         | 10     | _          | pF       |

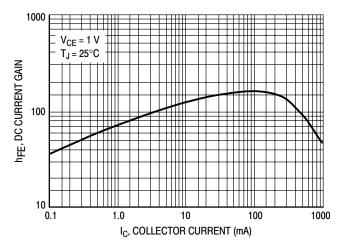


Figure 1. DC Current Gain

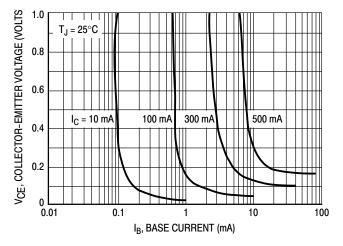


Figure 2. Saturation Region

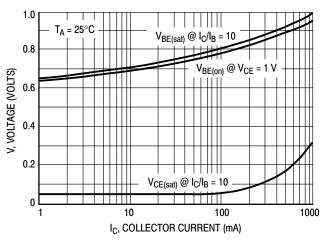
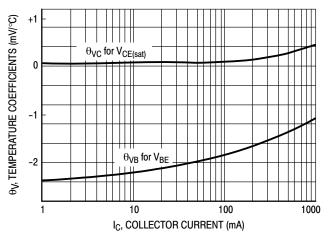


Figure 3. "On" Voltages



**Figure 4. Temperature Coefficients** 

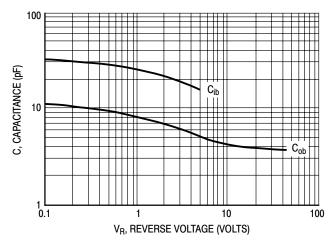
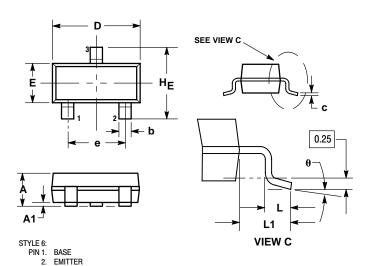


Figure 5. Capacitances

#### PACKAGE DIMENSIONS

### SOT-23 (TO-236) CASE 318-08 ISSUE AN

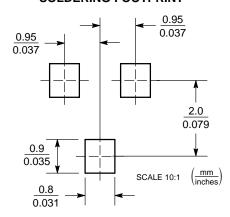


NOTES

- DIMENSIONING AND TOLERANCING PER ANSI
   Y14 FM 1092
- Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH.
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
- 4. 318-01 THRU -07 AND -09 OBSOLETE, NEW STANDARD 318-08.

|     | MILLIMETERS |      |      |       |       |       |
|-----|-------------|------|------|-------|-------|-------|
| DIM | MIN         | NOM  | MAX  | MIN   | NOM   | MAX   |
| Α   | 0.89        | 1.00 | 1.11 | 0.035 | 0.040 | 0.044 |
| A1  | 0.01        | 0.06 | 0.10 | 0.001 | 0.002 | 0.004 |
| b   | 0.37        | 0.44 | 0.50 | 0.015 | 0.018 | 0.020 |
| С   | 0.09        | 0.13 | 0.18 | 0.003 | 0.005 | 0.007 |
| D   | 2.80        | 2.90 | 3.04 | 0.110 | 0.114 | 0.120 |
| E   | 1.20        | 1.30 | 1.40 | 0.047 | 0.051 | 0.055 |
| е   | 1.78        | 1.90 | 2.04 | 0.070 | 0.075 | 0.081 |
| L   | 0.10        | 0.20 | 0.30 | 0.004 | 0.008 | 0.012 |
| L1  | 0.35        | 0.54 | 0.69 | 0.014 | 0.021 | 0.029 |
| HE  | 2.10        | 2.40 | 2.64 | 0.083 | 0.094 | 0.104 |

### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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